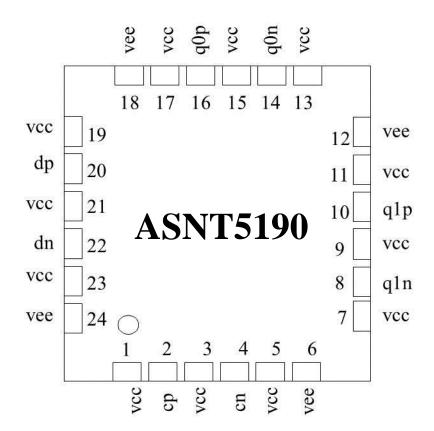


Ultra High-Speed Mixed Signal ASICs

Offices: 310-530-9400 / Fax: 310-530-9402 www.adsantec.com

ASNT5190-PQC DC-36*Gbps* Broadband Digital 1:2 Demultiplexer

- High speed broadband 1:2 Demultiplexer
- Exhibits low jitter and limited temperature variation over industrial temperature range
- Ideal for high speed proof-of-concept prototyping
- Fully differential CML input interfaces
- Fully differential CML output interface with 400mV single-ended swing
- Single +3.3V or -3.3V power supply
- Power consumption: 495*mW*
- Fabricated in SiGe for high performance, yield, and reliability
- Standard MLF/QFN 24-pin package





DESCRIPTION

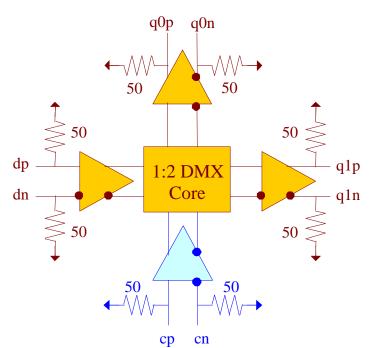


Fig. 1. Functional Block Diagram

The temperature stable ASNT5190-PQC SiGe IC can be utilized as a high speed 1:2 demultiplexer, and is intended for use in high-speed measurement / test equipment. The IC shown in Fig. 1 can receive a high speed differential data input signal dp/dn and effectively demultiplex it into two high speed differential data output signals q0p/q0n and q1p/q1n by using a high speed differential clock input signal cp/cn.

The part's I/O's support the CML logic interface with on chip 50*Ohm* termination to **vcc** and may be used differentially, AC/DC coupled, single-ended, or in any combination (see also POWER SUPPLY CONFIGURATION). In the DC-coupling mode, the input signal's common mode voltage should comply with the specifications shown in ELECTRICAL CHARACTERISTICS. In the AC-coupling mode, the input termination provides the required common mode voltage automatically. The differential DC signaling mode is recommended for optimal performance.

POWER SUPPLY CONFIGURATION

The part can operate with either negative supply (vcc = 0.0V = ground and vee = -3.3V), or positive supply (vcc = +3.3V and vee = 0.0V = ground). In case of the positive supply, all I/Os need AC termination when connected to any devices with 50*Ohm* termination to ground. Different PCB layouts will be needed for each different power supply combination.



All the characteristics detailed below assume VCC = 0.0V and Vee = -3.3V.

ABSOLUTE MAXIMUM RATINGS

Caution: Exceeding the absolute maximum ratings may cause damage to this product and/or lead to reduced reliability. Functional performance is specified over the recommended operating conditions for power supply and temperature only. AC and DC device characteristics at or beyond the absolute maximum ratings are not assumed or implied. All min and max voltage limits are referenced to ground (assumed vcc).

Parameter	Min	Max	Units
Supply Voltage (vee)		-3.6	V
Power Consumption		0.65	W
RF Input Voltage Swing (SE)		1.0	V
Case Temperature		+90	°С
Storage Temperature	-40	+100	°С
Operational Humidity	10	98	%
Storage Humidity	10	98	%

Table 1. Absolute Maximum Ratings

TERMINAL FUNCTIONS

TERMINAL			DESCRIPTION			
Name	No.	Туре				
High-Speed I/Os						
dp	20	CML	Differential data input signals with internal 500hm termination			
dn	22	input	to VCC			
q0p	16	CML	Differential data output signals with internal 500hm			
q0n	14	output	termination to VCC			
q1p	10	CML	Differential data output signals with internal 500hm			
q1n	8	output	terminatio	n to VCC		
ср	2	CML	Differential clock input signals with internal 500hm			
cn	4	input	terminatio	n to VCC		
Supply and Termination Voltages						
Name	Description			Pin Number		
vcc	Positive power supply		r supply	1, 3, 5, 7, 9, 11, 13, 15, 17, 19, 21, 23		
	(+3.3V or 0)		: 0)			
vee	Negative power supply		er supply	6, 12, 18, 24		
	(0V or -3.3V)		3V)			



ELECTRICAL CHARACTERISTICS

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS	
General Parameters						
vee	-3.1	-3.3	-3.5	V	$\pm 6\%$	
VCC		0.0		V	External ground	
Ivee	120	150	180	mА		
Power consumption	370	495	630	mW		
Junction temperature	-40	25	125	°C		
		H	S Input D)ata (dp/c	in)	
Data rate	DC		36	Gbps		
Swing	0.05		1.0	V	Differential or SE, p-p	
CM Voltage Level	vcc-0.8		VCC	V	Must match for both inputs	
		HS	5 Input C	lock (cp/	cn)	
Frequency	DC		18	GHz		
Swing	0.05		1.0	V	Differential or SE, p-p	
CM Voltage Level	vcc-0.8		VCC	V	Must match for both inputs	
Duty cycle	45	50	55	%		
	H	IS Outp	ut Data (q0p/q0n,	q1p/q1n)	
Data rate	DC		18	Gbps		
Logic "1" level		VCC		V		
Logic "0" level		vcc-0.4		V	With external 500hm DC termination	
Rise/Fall times	14	18	22	ps	20%-80%	
Output Jitter			1	ps	Peak-to-peak	

PACKAGE INFORMATION

The chip die is housed in a standard 24-pin QFN package shown in Fig. 2. It is recommended that the center heat slug located on the back side of the package is soldered to the **vee** plain that is ground for the positive supply or power for the negative supply.

The part's identification label is ASNT5190-PQC. The first 8 characters of the name before the dash identify the bare die including general circuit family, fabrication technology, specific circuit type, and part version while the 3 characters after the dash represent the package's manufacturer, type, and pin out count.

This device complies with the Restriction of Hazardous Substances (RoHS) per 2011/65/EU for all ten substances.





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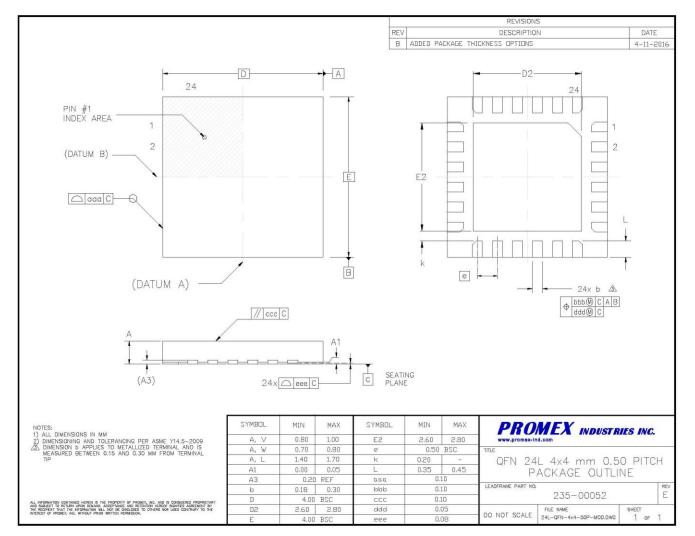


Fig. 2. QFN 24-Pin Package Drawing (All Dimensions in mm)



REVISION HISTORY

Revision	Date	Changes			
1.1.2	01-2020	Updated Package Information			
1.0.2	07-2019	Updated Letterhead			
1.0.1	11-2017	First release			